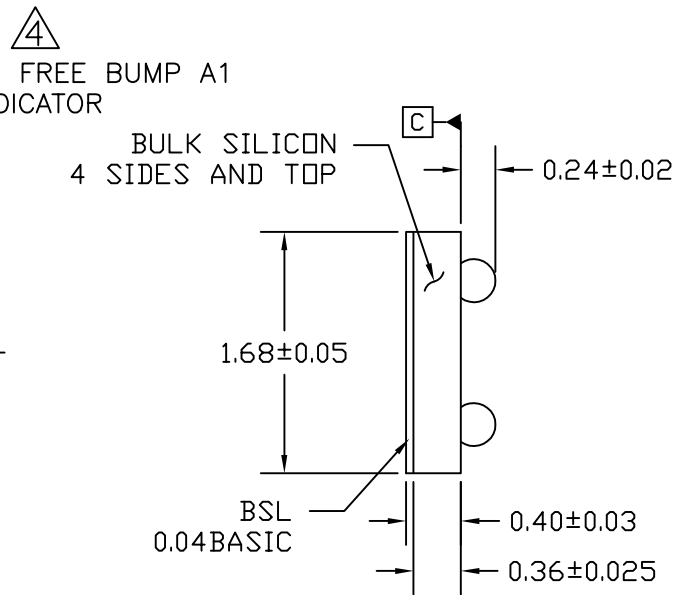
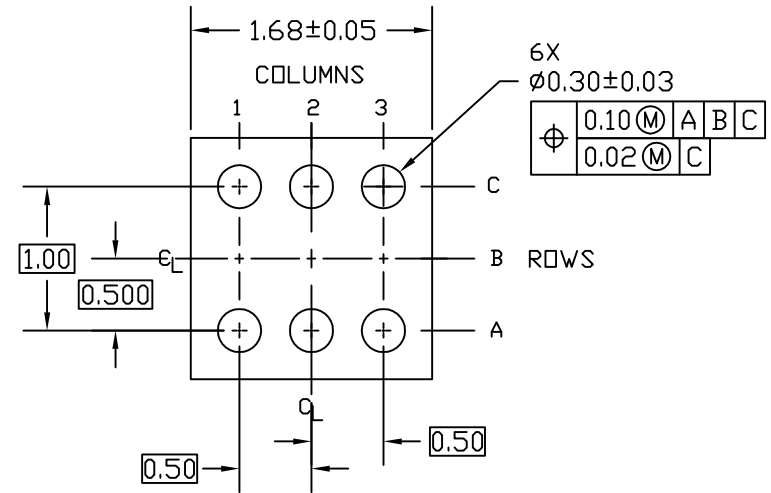


TOP VIEW



SIDE VIEW



BOTTOM VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. BUMP MATERIAL: SAC125Ni
4. LASER MARK INDICATING A1 CORNER ORIENTATION. NUMBER OF CHARACTERS AND LINES VARY BY PRODUCT.
5. ELECTRICAL NODES -- SEE PRODUCT DATA SHEET OR PROBE DOCUMENT.
6. DEPOPULATED SOLDER BALLS: B1, B2, B3.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
8. PACKAGE CODE: BR622-1



TITLE: PACKAGE OUTLINE, 0.50mm GRID 3X3 BALL ARRAY USED ON DS2431 PbFree			
APPROVAL	DOCUMENT CONTROL NO. 21-0376	REV. C	1/1

-DRAWING NOT TO SCALE-